

What is claimed is:

1. A module component comprising:

a substrate having connection electrodes metalized thereon; and

5 a plurality of components orderly mounted on the substrate in the longitudinal direction of the substrate, and electrically connected to the connection electrodes via bumps,

wherein the heights of the bumps connecting the plurality of components to the connection electrodes of the substrate are set to be larger in the direction toward the edge of the substrate, being referenced from the height of the bump positioned in the center area of the substrate in the longitudinal direction of the substrate.

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2. A module component comprising:

a substrate having connection electrodes metalized thereon; and

a component mounted on the substrate, and electrically connected to the connection electrodes via bumps,

20 wherein the component is connected to the connection electrodes with at least three bumps in the longitudinal direction of the substrate, and

the heights of the plurality of bumps are set to be larger in the direction toward the edge of the substrate, being referenced from the height of the bump positioned in the center area.

3. A module component comprising:

a substrate having connection electrodes metalized thereon; and

5 a plurality of components orderly mounted on the substrate in the longitudinal direction of the substrate, and electrically connected to the connection electrodes via bumps,

wherein the heights of the connection electrodes to which the plurality of components are connected via the bumps are set to be larger in the direction toward the edge of the substrate, being referenced from the height of the connection electrode corresponding to the bump positioned in the center area of the substrate.

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4. A module component comprising:

a substrate having connection electrodes metalized thereon; and

20 a component mounted on the substrate, and electrically connected to the connection electrodes via bumps,

wherein the component is connected to the connection electrodes with at least three bumps in the longitudinal direction of the substrate, and

25 the heights of the respective connection electrodes corresponding to the plurality of bumps are set to be larger in the direction toward the edge of the substrate, being referenced from the height of the connection electrode

corresponding to the bump positioned in the center area.

5. The module component according to any of claim 1 to claim 4,

5 wherein the substrate is a ceramic substrate burnt after the electrodes are metalized on an alumina layer.

6. The module component according to any of claim 1 to claim 4,

10 wherein the component is a surface acoustic wave element having comb electrodes formed on the face opposite to the substrate on which the element is mounted via the bumps, and the component is sealed with both a package chip formed in the periphery of the substrate and a cap structure.

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7. The module component according to claim 3 or claim 4,

wherein the heights of the connection electrodes are set by the number of layers of the connection electrodes.

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8. A module component comprising:

a first substrate having connection electrodes metalized thereon;

a first component mounted on the first substrate, and  
25 electrically connected to the connection electrodes via bumps;

a second substrate of which an area corresponding to

the first component is hollowed out, laminated on the first substrate, and having connection electrodes metalized thereon; and

5 a second component mounted on the second substrate above the first components, and electrically connected to the connection electrodes via bumps,

wherein either the first component or the second component is constituted of a plurality of components, and

10 the plurality of components are orderly mounted on the corresponding first or second substrate, and

the heights of the connection electrodes to which the plurality of components are connected via the bumps are set to be larger in the direction toward the edge of the first or second substrate, being referenced from the height  
15 of the connection electrode corresponding to the bump positioned in the center area of the corresponding first or second substrate in the longitudinal direction.

9. A module component comprising:

20 a first substrate having connection electrodes metalized thereon;

a first component mounted on the first substrate, and electrically connected to the connection electrodes via bumps;

25 a second substrate of which an area corresponding to the first component is hollowed out, laminated on the first substrate, and having connection electrodes metalized

thereon; and

a second component mounted on the second substrate above the first components, and electrically connected to the connection electrodes via bumps,

5        wherein either the first component or the second component is connected to the connection electrodes with at least three bumps in the longitudinal direction of the corresponding first or second substrate, and the heights of the plurality of bumps are set to be larger in the  
10        direction toward the edge of the corresponding first or second substrate, being referenced from the height of the bump positioned in the center area.

10. The module component according to claim 8 or claim  
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wherein the component is a surface acoustic wave element having comb electrodes formed on the face opposite to the substrate, on which the element is mounted via the bumps, and the component is sealed with both a package chip  
20        formed in the periphery of the substrate and a cap structure.

11. The module component according to claim 8 or claim  
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wherein the substrate is a ceramic substrate burnt  
25        after the electrodes are metalized on an alumina layer.

12. The module component according to claim 8,

wherein the heights of the connection electrodes are set by the number of layers of the connection electrodes.